



PATENT
8013-1147

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Hirokazu HONDA Conf. 7187

Application No. 09/678,609 Group 2822

Filed October 4, 2000 Examiner D. Graybill

MULTILAYER INTERCONNECTION BOARD,
SEMICONDUCTOR DEVICE HAVING THE
SAME, AND METHOD OF FORMING THE
SAME AS WELL AS METHOD OF MOUNTING
THE SEMICONDUCTOR CHIP ON THE
INTERCONNECTION BOARD

AMENDMENT

MS RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

October 24, 2005

Sir:

In response to the Official Action of May 23, 2005,
please amend the application as follows:

Amendments to the Claims are reflected in the listing
of claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.